

preliminary

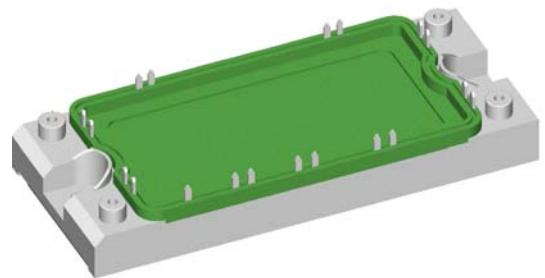
Standard Rectifier Module

3~ Rectifier	Brake Chopper
$V_{RRM} = 2200 \text{ V}$	$V_{CES} = 1700 \text{ V}$
$I_{DAV} = 150 \text{ A}$	$I_{C25} = 113 \text{ A}$
$I_{FSM} = 1100 \text{ A}$	$V_{CE(sat)} = 1.9 \text{ V}$

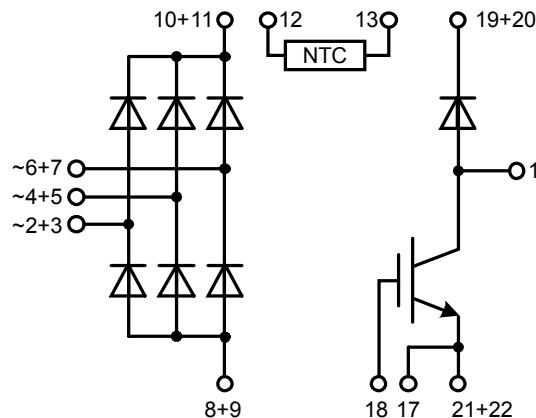
3~ Rectifier Bridge + Brake Unit + NTC

Part number

VUB135-22NO1



Backside: isolated



Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current
- NTC

Applications:

- 3~ Rectifier with brake unit for drive inverters

Package: E2-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: Copper internally DCB isolated
- Advanced power cycling

Rectifier

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
V_{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			2300	V
V_{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			2200	V
I_R	reverse current	$V_R = 2200 \text{ V}$ $V_R = 2200 \text{ V}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		100 2	μA mA
V_F	forward voltage drop	$I_F = 50 \text{ A}$ $I_F = 150 \text{ A}$ $I_F = 50 \text{ A}$ $I_F = 150 \text{ A}$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		1.20 1.68 1.13 1.74	V V
I_{DAV}	bridge output current	$T_C = 105^\circ C$ rectangular $d = 1/3$	$T_{VJ} = 150^\circ C$		150	A
V_{FO} r_F	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 150^\circ C$		0.79 6.4	V $m\Omega$
R_{thJC}	thermal resistance junction to case				0.5	K/W
R_{thCH}	thermal resistance case to heatsink			0.1		K/W
P_{tot}	total power dissipation		$T_C = 25^\circ C$		250	W
I_{FSM}	max. forward surge current	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 \text{ V}$		1.10 1.19	kA kA
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$ $V_R = 0 \text{ V}$		935 1.01	A kA
I^2t	value for fusing	$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 45^\circ C$ $V_R = 0 \text{ V}$		6.05 5.89	kA^2s kA^2s
		$t = 10 \text{ ms}; (50 \text{ Hz}), \text{sine}$ $t = 8,3 \text{ ms}; (60 \text{ Hz}), \text{sine}$	$T_{VJ} = 150^\circ C$ $V_R = 0 \text{ V}$		4.37 4.25	kA^2s kA^2s
C_J	junction capacitance	$V_R = 400 \text{ V}; f = 1 \text{ MHz}$	$T_{VJ} = 25^\circ C$	37		pF

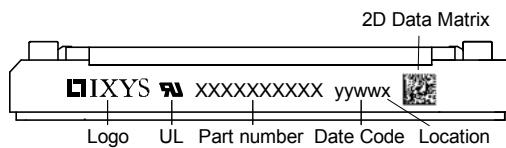
Brake IGBT

Symbol	Definition	Conditions	min.	typ.	max.	Unit	
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$			1700	V	
V_{GES}	max. DC gate voltage				± 20	V	
V_{GEM}	max. transient gate emitter voltage				± 30	V	
I_{C25}	collector current	$T_C = 25^\circ C$			113	A	
I_{C80}		$T_C = 80^\circ C$			80	A	
P_{tot}	total power dissipation	$T_C = 25^\circ C$			445	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 75 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$	1.9	2.13	V	
			$T_{VJ} = 125^\circ C$	2.8		V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 3 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.2	5.8	6.4	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$		0.6	mA	
			$T_{VJ} = 125^\circ C$	0.6		mA	
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			400	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 900 V; V_{GE} = 15 V; I_C = 75 A$		tbd		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 900 V; I_C = 75 A$ $V_{GE} = \pm 15 V; R_G = 18 \Omega$		220		ns	
t_r	current rise time			100		ns	
$t_{d(off)}$	turn-off delay time			880		ns	
t_f	current fall time			200		ns	
E_{on}	turn-on energy per pulse			30		mJ	
E_{off}	turn-off energy per pulse			25		mJ	
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 18 \Omega$	$T_{VJ} = 125^\circ C$				
I_{CM}		$V_{CEK} = 1700 V$			150	A	
SCSOA	short circuit safe operating area						
t_{sc}	short circuit duration	$V_{CE} = 900 V; V_{GE} = \pm 15 V$	$T_{VJ} = 125^\circ C$		10	μs	
I_{sc}	short circuit current	$R_G = 18 \Omega$; non-repetitive		tbd		A	
R_{thJC}	thermal resistance junction to case				0.28	K/W	
R_{thCH}	thermal resistance case to heatsink				0.10	K/W	

Brake Diode

V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$		1700	V
I_{F25}	forward current	$T_C = 25^\circ C$		tbd	A
I_{F80}		$T_C = 80^\circ C$		33	A
V_F	forward voltage	$I_F = 60 A$	$T_{VJ} = 25^\circ C$	3.05	V
			$T_{VJ} = 125^\circ C$	3.11	V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$	0.1	mA
			$T_{VJ} = 125^\circ C$	6	mA
Q_{rr}	reverse recovery charge	$V_R = 900 V$ $-di_F/dt = 400 A/\mu s$ $I_F = 60 A$		tbd	μC
				40	A
				tbd	ns
R_{thJC}	thermal resistance junction to case			0.65	K/W
R_{thCH}	thermal resistance case to heatsink			0.25	K/W

Package E2-Pack			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			200	A
T_{stg}	storage temperature		-40		125	°C
T_{VJ}	virtual junction temperature		-40		150	°C
Weight				176		g
M_D	mounting torque		3		6	Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air		terminal to terminal		6.0	mm
$d_{Spb/Apb}$			terminal to backside		12.0	mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 3000	V V



Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUB135-22NO1	VUB135-22NO1	Box	6	503948

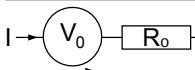
Temperature Sensor NTC

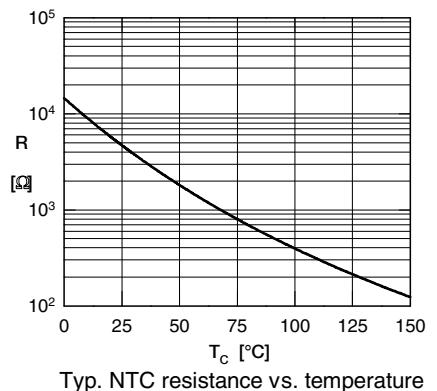
Symbol	Definition	Conditions	min.	typ.	max.	Unit
R_{25}	resistance	$T_{VJ} = 25^\circ C$	4.75	5	5.25	kΩ
$B_{25/50}$	temperature coefficient			3375		K

Equivalent Circuits for Simulation

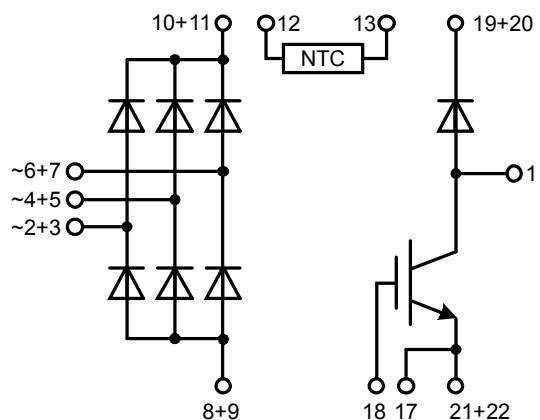
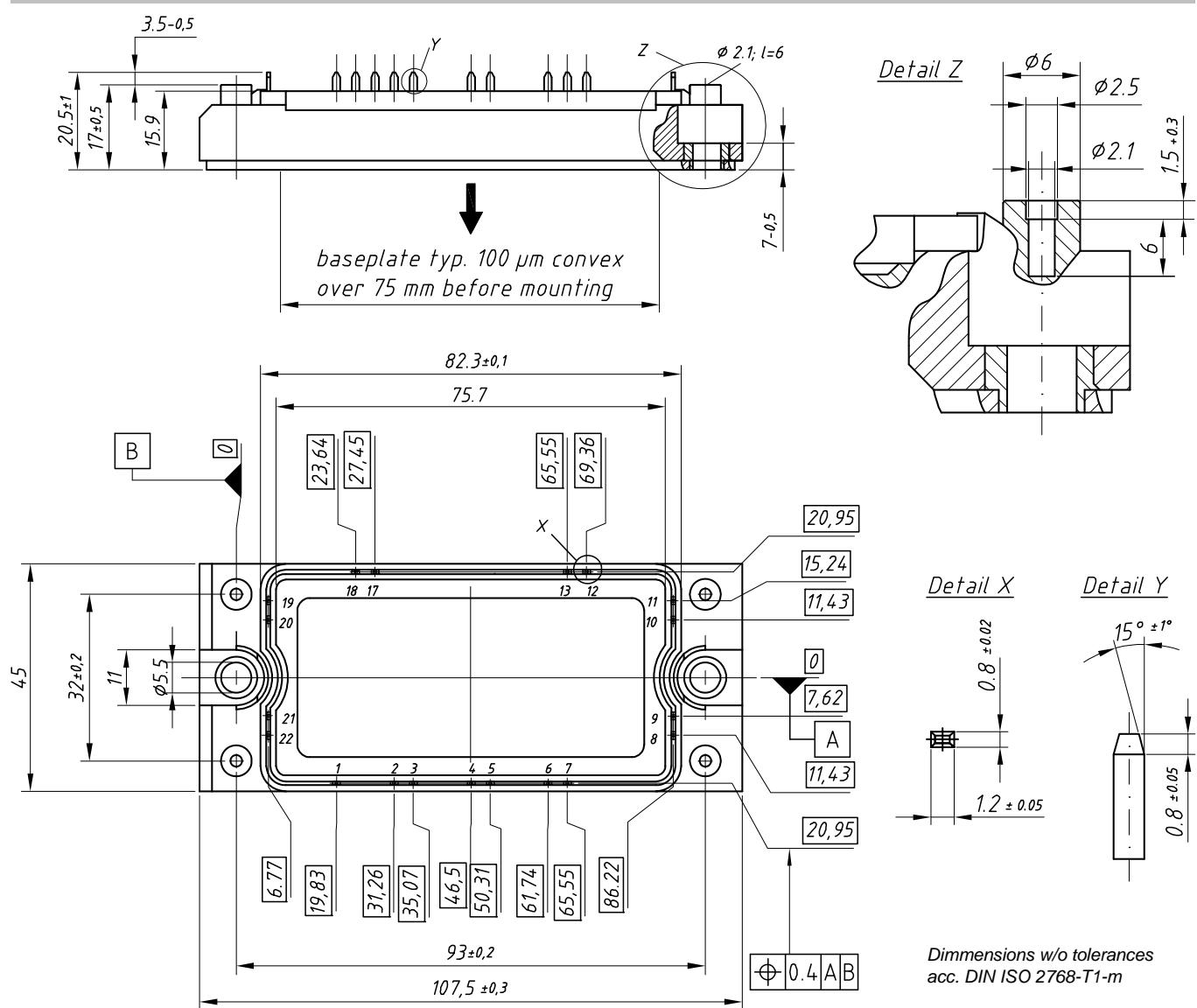
* on die level

 $T_{VJ} = 150^\circ C$

	Rectifier
$V_{0\max}$	threshold voltage
$R_{0\max}$	slope resistance * 3.3



Outlines E2-Pack



Rectifier

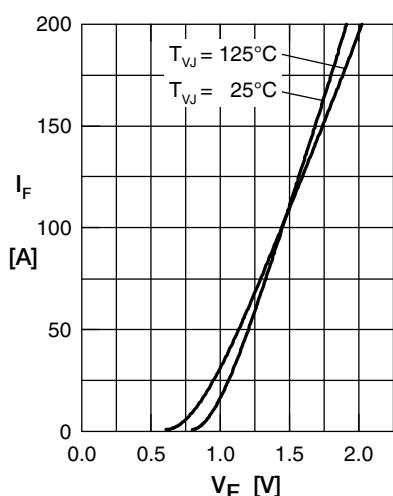


Fig. 1 Forward current vs.
voltage drop per diode

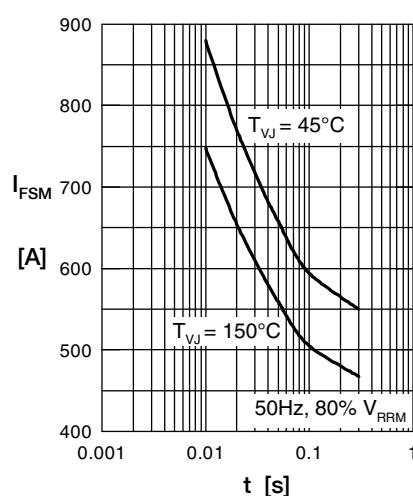


Fig. 2 Surge overload current
vs. time per diode

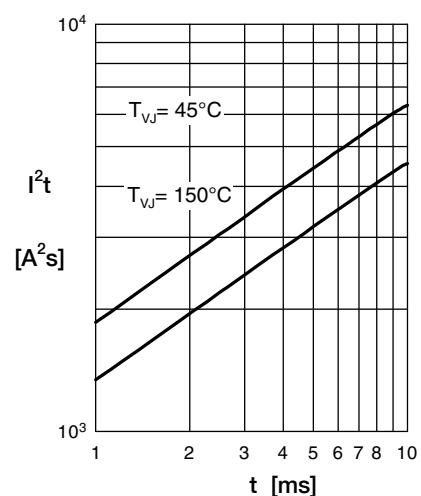


Fig. 3 I^2t vs. time per diode

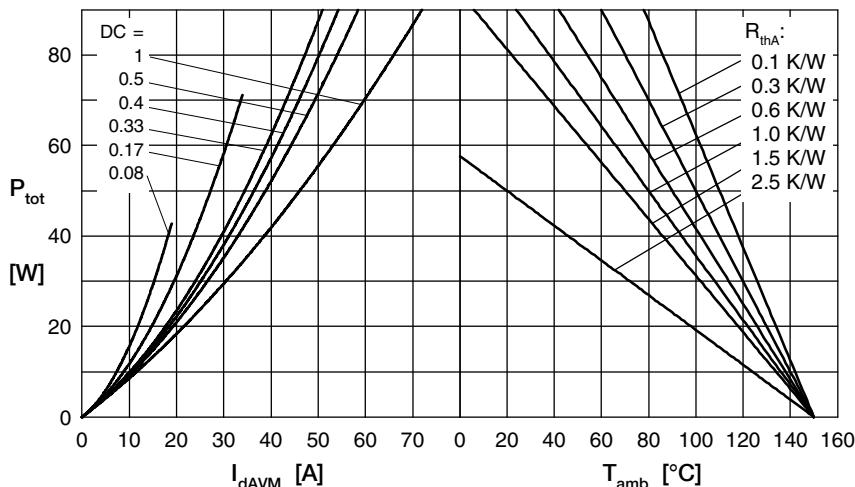


Fig. 4 Power dissipation vs. forward current
and ambient temperature per diode

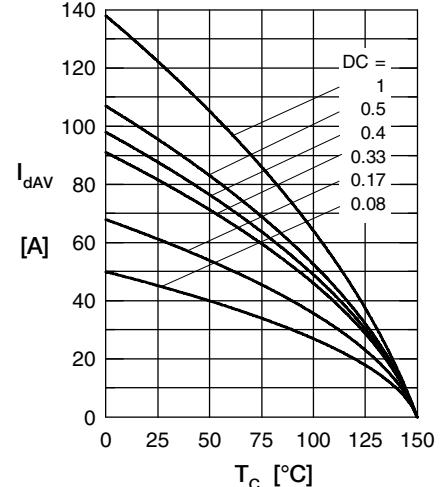


Fig. 5 Max. forward current vs.
case temperature per diode

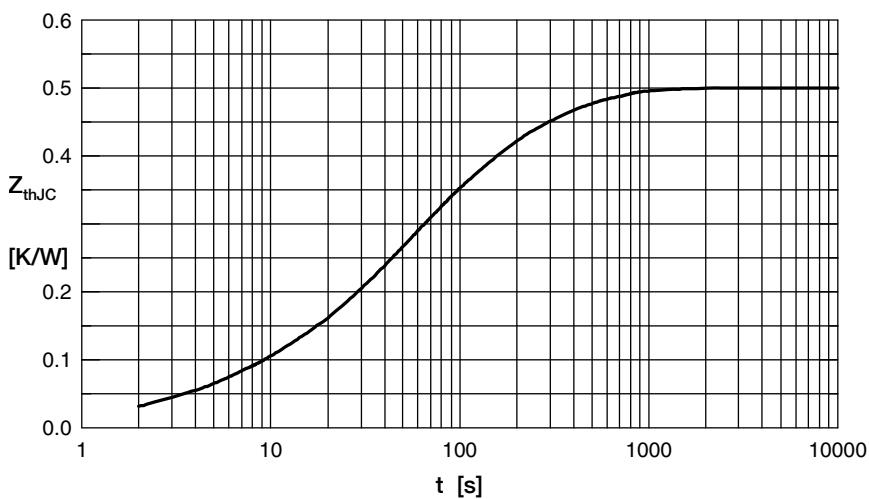


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for Z_{thJC} calculation:

i	R_{th} (K/W)	t_i (s)
1	0.040	0.004
2	0.003	0.010
3	0.140	0.030
4	0.120	0.300
5	0.197	0.080